

DEK ProFlow® ATx

STATE-OF-THE-ART PRINT HEAD TECHNOLOGY
FOR MORE EFFICIENCY



Having a reliable and efficient solder paste printing system is a prerequisite for the Smart #1 SMT Factory, and the enclosed DEK ProFlow® ATx print head system for fully automated printing processes delivers.

You benefit from improved efficiency and process stability thanks to consistent print quality, fewer manual assists, less waste, and a higher yield.



Printing solder paste – due to the highest requirements of today's very small components – requires stable conditions for achieving consistent printing results. DEK's ProFlow® technology sets new standards and makes the paste application process fully controllable with its enclosed system. This means fast solder paste printing without quality fluctuations and interruptions. The DEK ProFlow® ATx represents the latest generation of this trailblazing technology.

Your benefits at a glance:

Print process

- Active controlled grid ensures perfect paste conditioning
- Excellent printing results for many SMT applications, including pin-in-paste
- Even paste distribution across the entire squeegee width
- Consistent solder paste application under stable process conditions

Paste compatibility

- Handles all popular paste types with standard set of parameters

Maintenance

- Long cleaning cycles (up to six months)
- Minimal manual assists
- Quick and easy head replacement

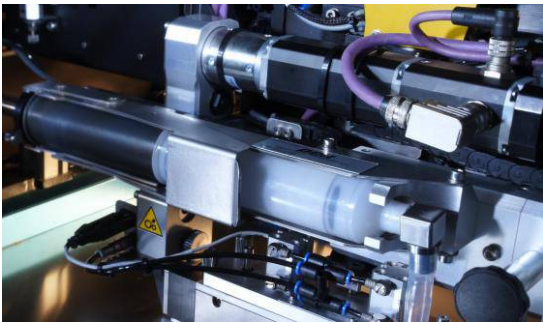
Cost of ownership

- Uses standard cartridges (12 oz/6 oz); no special ProFlow® cassettes required
- Significant reduction in paste wastage cuts costs considerably

DEK ProFlow® ATx

More efficiency

DEK ProFlow® ATx is an exceptionally flexible print head for precise stencil printing in the Smart #1 SMT Factory. Usable on the DEK NeoHorizon iX, DEK Horizon and DEK Galaxy series of printers, this enclosed printing system works with all common solder paste types and viscosities.



DEK ProFlow® ATx – the technology of choice for the Smart #1 SMT Factory.

Fully automatic paste management

The Archimedean screw in the DEK ProFlow® ATx guarantees that the head is evenly filled with solder paste. In addition, the paste plunger in the ATx system ensures that apertures are filled evenly by exerting vertical pressure to the paste.

Your benefit: fully automatic paste management for your printing process.

The combination of DEK printer and DEK ProFlow® ATx delivers a reliable, fast and perfectly balanced printing process with a minimum of maintenance.

Consistent rheological conditions

The active controlled grid system of the DEK ProFlow® ATx, which is controlled by the DEK software, ensures optimal paste viscosity and flow behavior at all times for maximum process stability.

This level of consistency enables you to master any challenge in modern SMT production: solder pads for large or extra-small components, SMT/THT combinations, pin-in-paste, and other applications.

TECHNICAL SPECIFICATIONS

DEK machine platforms	Horizon iX, NeoHorizon iX, Galaxy
Retrofitting (MPU)	Possible on the above platforms
Cartridge sizes	Standard 12 oz. and 6 oz. cartridges
ATx 300 printing area (width)	Recommended : 200 mm x 295 mm Maximum printing width: 295 mm
ATx 400 printing area (width)	Recommended : 295 x 395mm Maximum printing width: 395 mm
Printing materials	Materials with increased viscosity (non-Newtonian), such as SMT solder pastes
Notes	<ul style="list-style-type: none">Compatibility with stepped stencils must be checked on a case-by-case basis.In some cases, the stencil design must be modified to accommodate larger apertures.

ASM Assembly Systems GmbH & Co. KG
Rupert-Mayer-Str. 44
81379 Munich, Germany
Tel: +49 89 20800-27819
Fax: +49 89 20800-36692
smt-solutions.de@asmpt.com

www.asm-smt.com

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